

Amendments to the Claims:

Please cancel claims 21-23. Following is a complete listing of the claims as amended:

1. (Original) A selectively configurable circuit board, comprising:
a substrate having at least one component site adapted to receive a microelectronic component;
a plurality of board leads adapted to interface the circuit board with an external bus;
a plurality of board contacts arranged adjacent the component site, each of the board contacts being adapted to be electrically coupled to a component contact of a microelectronic component which may be received at the component site; and
selectively configurable circuitry carried by the substrate and adapted to selectively couple selected ones of the board contacts to selected ones of the board leads, the selectively configurable circuitry comprising at least one trace associated with each of the electrical connectors, at least one of the traces including a normally open thermally actuatable switch which can be selectively closed to create an electrical connection.
2. (Original) The selectively configurable circuit board of claim 1 wherein the thermally actuatable switch comprises a gap between two conductive lengths of the conductive trace and a thermally responsive member.
3. (Original) The selectively configurable circuit board of claim 1 wherein the thermally actuatable switch comprises a gap between two conductive lengths of the conductive trace, an exposed switch surface, and a thermally responsive member.
4. (Original) The selectively configurable circuit board of claim 3 wherein the thermally responsive member is formed of a thermally responsive material which

will wet the exposed switch surface when selectively heated above an activation temperature.

5. (Original) The selectively configurable circuit board of claim 4 wherein the activation temperature comprises a melting point of the thermally responsive material.

6. (Original) The selectively configurable circuit board of claim 4 wherein the activation temperature comprises a glass transition temperature of the thermally responsive material.

7. (Original) The selectively configurable circuit board of claim 1 wherein the thermally actuatable switch comprises a gap between a first conductive length and a second conductive length of the conductive trace, a gap surface between the first and second conductive lengths, and a fusible member, the first conductive length being formed of a first conductive material and the second conductive length being formed of a second conductive material, the fusible member being formed of a fusible material which will flow to wet the gap surface at a temperature below a melting point of the first conductive material and a melting point of the second conductive material.

8. (Original) The selectively configurable circuit board of claim 1 wherein a plurality of the traces each include a normally open thermally actuatable switch which can be selectively closed to create an electrical connection.

9. (Original) The selectively configurable circuit board of claim 1 wherein a plurality of the traces each include a normally open thermally actuatable switch which can be selectively closed to create an electrical connection, each of the thermally actuatable switches being adapted to be individually closed in response to a localized thermal stimulus without necessitating closure of any other thermally actuatable switch.

10. (Original) The selectively configurable circuit board of claim 1 further comprising a closed switch in one of the traces, the closed switch comprising a normally open thermally actuatable switch which has been thermally actuated to create an electrical connection.

11-42. (Canceled)


Conclusion

Upon reviewing the file for this application, it came to the undersigned's attention that claims 21-23 have not been formally cancelled in this application. To avoid any ambiguity on the record, the present amendment cancels claims 21-23.

The undersigned respectfully requests consideration and entry of this amendment. If the Examiner has any questions, he is encouraged to call the undersigned at (206) 359-3848.

Respectfully submitted,
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